

PRODUCT/PROCESS CHANGE NOTIFICATION

PCN IPD-DIS/13/7944 Dated 21 Jun 2013

New ECOPACK2 molding compound for selected products housed in TO-220AB, TO-220AB insulated, TO-220AC insulated and D2PAK

Forecasted implementation date for change	20-Sep-2013
Forecasted availability date of samples for customer	28-Jun-2013
Forecasted date for STMicroelectronics change Qualification Plan results availability	14-Jun-2013
Estimated date of changed product first shipment	20-Sep-2013

Table 2. Change Identification

Product Identification (Product Family/Commercial Product)	TO-220AB, TO-220AB ins, TO-220AC ins and D2PAK
Type of change	Package assembly material change
Reason for change	to meet the latest environmental standards
Description of the change	ST selected products housed in TO-220AB, TO-220AB insulated, TO-220AC insulated and D2PAK packages are upgraded to the ECOPACK2 level by changing its current compound to Halogen free.
Change Product Identification	internal codification, QA number, date code, marking
Manufacturing Location(s)	

Table 3. List of Attachments

Customer Part numbers list	
Qualification Plan results	

Customer Acknowledgement of Receipt	PCN IPD-DIS/13/7944
Please sign and return to STMicroelectronics Sales Office	Dated 21 Jun 2013
Qualification Plan Denied	Name:
Qualification Plan Approved	Title:
	Company:
🗖 Change Denied	Date:
Change Approved	Signature:
Remark	

Name	Function	
Paris, Eric	Marketing Manager	
Duclos, Franck	Product Manager	
Cazaubon, Guy	Q.A. Manager	

DOCUMENT APPROVAL



(1) IPD: Industrial & Power Discretes - ASD: Application Specific Device – IPAD™: Integrated Passive and Active Devices

PCN Product/Process Change Notification

New ECOPACK®2 molding compound for selected products housed in TO-220AB, TO-220AB insulated, TO-220AC insulated and D2PAK

Notification number:	IPD-DIS/13/7944	Issue Date	14/06/2013
Issued by	Aline AUGIS		
Product series affected by the change		See change implementation	schedule table
Type of change		Assembly package material change	

Description of the change

ST selected products housed in **TO-220AB**, **TO-220AB** insulated, **TO-220AC** insulated and **D2PAK** packages are upgraded to the **ECOPACK**[®]2 level by changing its current compound to Halogen free.

Reason for change

ST willingness is to meet the latest environmental standards and convert therefore its portfolio to the so called "Halogen-Free" requirements.

The changed products do not present modified electrical, dimensional or thermal parameters, leaving unchanged the current information published in the product datasheet The Moisture Sensitivity Level of the part (according to the IPC/JEDEC JSTD-020D standard) remains unchanged. The footprint recommended by ST remains the same. There is no change in the packing modes and the standard delivery quantities either.

Disposition of former products

Deliveries of former product will continue while the conversion is brought to completion and as long as former product stocks last.

Marking and traceability

Date code, QA number, internal codification (internal code mentioned on the label) and a letter "G" printed to the right of the "e3" symbol on the marking.





(1) IPD: Industrial & Power Discretes - ASD: Application Specific Device – IPAD™: Integrated Passive and Active Devices

alification complete date		W23-2013		
orecasted sample availability				
.Product family	Sub-family	Commercial part Number	Availability date	
		T1635T-6I T1650H-6I	W26	
		BTA06-600CRG BTA08-300BLRG BTA08-600CRG BTA12-600BRG BTA12-600BWRG BTA12-600CRG BTA16-600BWRG BTA16-600BWRG BTA16-800CWRG BTA24-400BWL BTA24-600BWRG TN1625-1000G-TR	W33	
Thyristors & AC Switches	Triacs	TYN612RG TYN616RG	W45	
		BTB12-600BWRG BTB16-600BWRG BTB16-600CWRG BTB16-600SWRG BTB16-700BWRG BTB16-700BWRG T1210-800G-TR T1235-800G-TR T1235H-6G-TR T1635H-6T T2050H-6T T2535-800G-TR T835-600G-TR	W46	
	Schottky Barrier Diodes	STPSC10TH13TI STPSC6TH13TI STPSC8TH13TI	W36	
Diodes and Rectifiers	Ultrafast Rectifiers	STTH1008DTI STTH1210DI STTH12R06DIRG STTH12T06DI STTH806DIRG STTH806DTI STTH810DI STTH812DI STTH8R04DI STTH8R04DI STTH8R06DIRG STTH8ST06DI	W36	
Protection	EOS protection	RBO40-40G-TR	W34	



(1) IPD: Industrial & Power Discretes - ASD: Application Specific Device – IPAD™: Integrated Passive and Active Devices

Change implementation schedule

	Sales types		Estimated production start	Estimated first shipments
BTA04-xxxSRG	BTA10-xxxBWRG	T1225T-6I		ompinento
BTA04-xxxTRG	BTA10-xxxCRG	T1235H-6I		
BTA06T-	BTA10-xxxCWRG	T1235T-6I		
xxxCWRG	BTA10-xxxGPRG	T1250H-6I		
BTA06-xxxARG	BTA12-xxxBRG	T1610T-6I		
BTA06-xxxARG	BTA12-xxxBWRG	T1610T-8I		
BTA06-xxxBRG	BTA12-xxxCRG	T1620T-6I		
BTA06-xxxBRG	BTA12-xxxCWRG	T1620T-8I		
BTA06-xxxBWRG	BTA12-xxxGBRG	T1625T-8I		
BTA06-xxxCRG	BTA12-xxxSWRG	T1635H-6I		
BTA06-xxxCWRG	BTA12-xxxTWRG	T1635T-6I		
BTA06-xxxGKRG	BTA16-xxxBRG	T1635T-8I		
BTA06-xxxGPRG	BTA16-xxxBWRG	T1650H-6I		
BTA06-xxxGVRG	BTA16-xxxCRG	T1650HT-6I	September 2013	September 2013
BTA06-xxxGZRG	BTA16-xxxCWRG	T2035H-6I		
BTA06-xxxSRG	BTA16-xxxSWRG	T3035H-6I		
BTA06-xxxSWRG	BTA20-xxxBWRG	T3050H-6I		
BTA06-xxxTRG	BTA20-xxxCWRG	T810T-6I		
BTA06-xxxTWRG	BTA20-xxxWH	T820T-6I		
BTA08-xxx300xx	BTA24-xxxBWL	T825T-6I		
BTA08-xxxBRG	BTA24-xxxBWLRG	T835H-6I		
BTA08-xxxBWRG	BTA24-xxxBWRG	T835T-6I		
BTA08-xxxCRG	BTA24-xxxCWRG	T850H-6I		
BTA08-xxxCWRG	BTA24-xxxGPLRG	TXDVxxxRG		
BTA08-xxxSRG	T1035H-6I	TXNxx12RG		
BTA08-xxxSWRG	T1210T-6I	TXNxx25RG		
BTA08-xxxTWRG	T1220T-6I			
BTA10-xxxBRG				



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Sales types		Estimated production start	Estimated first shipments	
AVSxxxx	T1035H-6T	T410-xxxT		
BTB04-xxxSAPRG	T1050H-6G	T435-xxxT		
BTB04-xxxTRG	T1050H-6T	T610H-6T		
BTB06-xxxBRG	T1205-600G-TR	T810-600G-TR		
BTB06-xxxBWRG	T1210-800G-TR	T810H-6G		
BTB06-xxxCRG	T1235-600G	T810H-6G-TR		
BTB06-xxxCWRG	T1235-600G-TR	T810H-6T		
BTB06-xxxDRG	T1235-800G-TR	T835-600G		
BTB06-xxxSWRG	T1235H-600TRG	T835-600G-TR		
BTB06-xxxTRG	T1235H-6G	T835H-6G		
BTB06-xxxTWRG	T1235H-6G-TR	T835H-6G-TR		
BTB08-xxxBRG	T1235H-6T	T835H-6T		
BTB08-xxxBWRG	T1250-600G-TR	T850H-6G		
BTB08-xxxCRG	T1250H-6G-TR	T850H-6G-TR		
BTB08-xxxCWRG	T1250H-6T	T850H-6T		
BTB08-xxxSRG	T1610-600G-TR	TB08A6C		
BTB08-xxxSWRG	T1610-800G-TR	TB12A6C		
BTB08-xxxTWRG	T1635-600G	TB16A6D		
BTB10-xxxBWRG	T1635-600G-TR	TB16A6Y		
BTB12-xxxBRG	T1635-700G-TR	TB25A6C		
BTB12-xxxBWRG	T1635-800G-TR	TB25A6D	December 2013	December 2013
BTB12-xxxCRG	T1635H-6G	TN1205H-6G		
BTB12-xxxCWRG	T1635H-6G-TR	TN1205H-6G-TR		
BTB12-xxxSWRG	T1635H-6T	TN1205H-6T		
BTB12-xxxTWRG	T1650-600G-TR	TN1215-xxxG		
BTB15-xxxBAKRG	T1650H-6G	TN1215-xxxG-TR		
BTB16-xxxBRG	T1650H-6T	TN1625-xxxG-TR		
BTB16-	T2035H-6G	TN2540-xxxG-TR		
xxxBWARG	T2035H-6G-TR	TYNx12DTRG		
BTB16-xxxBWRG	T2035H-6T	TYNx16SRG		
BTB16-xxxCRG	T2050H-6T	TYNxx10RG		
BTB16-xxxCWRG	T2535-600G	TYNxx12RG		
BTB16-xxxSWRG	T2535-600G-TR	TYNxx12TRG		
BTB24-xxxBAKRG	T2535-800G	TYNxx16RG		
BTB24-xxxBRG	T2535-800G-TR	TYNxx25RG		
BTB24-xxxBWRG	T2550H-600TRG	TYNxx40RG		
BTB24-xxxCWRG	T3035H-6T	TYNxx4RG		
T1010H-6G	T3050H-6T	TYNxx6RG		
T1010H-6T	T405-xxxT	TYNxx8BDRG		
T1035H-6G	T410H-6T	TYNxx8RG		
T1035H-6G-TR				



(1) IPD: Industrial & Power Discretes - ASD: Application Specific Device – IPAD™: Integrated Passive and Active Devices

	production st	Estimated first art shipments
RB008-40G		
RBO08-40G-TR	December 20	12 December 2012
RBO40-40G	December 20	13 December 2013
RBO40-40G-TR		
BYT08PI-400RG		
STPSC10TH13TI		
STPSC6TH13TI		
STPSC8TH13TI		
STTHxxxDTI		
STTHxxxTTI		
STTHxxxDI	September 20	September 2013
STTH12R06DIRG		
STTHxxT06DI		
STTH806DIRG		
STTH8R04DI		
STTH8R06DIRG		
STTH8ST06DI		
STTH8T06TI		
TNxxxG(-TR)		
TNxxxT		
TXNxxxG	December 20	13 December 2013
TXN616B		
TYNxxxG		
Comments:	Others products housed	in D2PAK and TO220 not
	-	s PCN are not affected by
Customer's feedback		
Please contact your local ST sales representative or qu notification.	ality contact for requests co	ncerning this change

Absence of acknowledgement of this PCN within 30 days of receipt will constitute acceptance of the change Absence of additional response within 90 days of receipt of this PCN will constitute acceptance of the change

N° 13164QRP Attached
Ν



External Reliability Report

New ECOPACK®2 molding compound for selected products housed in TO-220AB, T0220ABinsulated, TO-220AC insulated and D²PAK

Gener	al Information	Locations		
Product Lines	AC Switches, Diodes Wafer fab		STMicroelectronics Tours (France)	
Products Description	TRIAC / SCR / Rectifier/ ASD	Assembly plant	STMicroelectronics SHENZHEN (China)	
Product Group	IPD	Reliability Lab	STMicroelectronics Tours (France)	
Product division	ASD&IPAD	Reliability assessment	PASS	
Package	TO-220AB,TO-220AB Insulated, TO-220AC-insulated, D²PAK			

DOCUMENT INFORMATION

Version	Date Pages Prepared by		Approved by	Comment	
Rev. 1	June 5 th 2013	22	Gilles DUTRANNOY	Jean-Paul REBRASSE	First issue

Note: This report is a summary of the reliability trials performed in good faith by STMicroelectronics in order to evaluate the potential reliability risks during the product life using a set of defined test methods.

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1 APPLICABLE AND REFERENCE DOCUMENTS

Document reference	Short description
JESD 47	Stress-Test-Driven Qualification of Integrated Circuits
MIL-STD-750C	Test method for semiconductor devices
SOP 2614	Reliability requirements for product qualification (ST internal document)
SOP 267	Product maturity levels (ST internal document)
0061692	Reliability tests and criteria for qualifications (ST internal document)
PCN reference	IPD-DIS/13/7944

2 GLOSSARY

BOM	Bill Of Materials
DUT	Device Under Test
F/G	Finished Good
HTRB	High Temperature Reverse Bias
PCT	Pressure Cooker Test
P/N	Part Number
RH	Relative Humidity
SS	Sample Size
ТСТ	Temperature Cycling Test
THB	Temperature Humidity Bias
HTS	High Temperature Storage
UPS	Uninterruptible Power Supply



<u>3 RELIABILITY EVALUATION OVERVIEW</u>

3.1 Objectives

ST products housed in **TO-220AB**, **T0220AB-insulated**, **TO-220AC insulated and D²PAK package** are upgraded to ECOPACK[®]2 level by changing its current compound to Halogen free.

3 product families are involved in this qualification: TRIAC and SCR, RECTIFIER and PROTECTION

3.2 Conclusion

Qualification Plan requirements have been fulfilled without exception. Reliability tests have shown that the devices behave correctly against environmental tests (no failure). Moreover, the stability of electrical parameters during the accelerated tests demonstrates the robustness of the product which is consequently expected during their lifetime.



Device Characteristics

3.3 **Device descriptions**



25 A standard and Snubberless™ triacs

Features

- High current triac
- Low thermal resistance with clip bonding.
- High commutation (4 quadrant) or very high commutation (3 quadrant) capability
- BTA series UL1557 certified (File ref: 81734)
- Packages are RoHS (2002/95/EC) compliant

Applications

Applications include the ON/OFF function in applications such as static relays, heating regulation, induction motor starting circuits, etc., or for phase control operation in light dimmers, motor speed controllers, and similar.

The snubberless versions (BTA/BTB...W and T25 series) are especially recommended for use on inductive loads, due to their high commutation performances. The BTA series provides an insulated tab (rated at 2500 V_{RMS}).

Description

Available either in through-hole or surface-mount packages, the BTA24, BTB24, BTA25, BTA26, BTB26 and T25 triac series is suitable for general purpose mains power AC switching. Table 1. Device summary								
Symbol	Parameter	BTA24 ⁽¹⁾	BTB24	BTA25 ⁽¹⁾	BTA26 ⁽¹⁾	BTB26	T25	Unit
I _{T(RMS)}	RMS on-state current	25	25	25	25	25	25	A
VDRM/VRRM	Repetitive peak off-state voltage	600/800	600 / 800	600 / 800	600 ⁽²⁾ / 800	600	600 / 800	v
I _{GT} (Snubberless)	Triggering gate current	35/50	35 / 50	50	35 / 50	-	35	mA
l _{GT} (Standard)	Triggering gate current	-	50	50	50	50	-	mA

Insulated packages 1.

2. 600 V version available only with $l_{\rm GT}$ = 50 mA (Snubberless and Standard)

TW: Snubberless is a trademark of STMicroelectronics



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T3035H, T3050H

TO-220AB insulated

(T30xxH-6I)

Value

30 A

600 V

35 or 50 mA

Snubberless™ high temperature 30 A Triacs

TO-220AB

(T30xxH-6T)

Symbol

 $h_{(me)}$

VDRM/VRRM

IGT

Device summary

Table 1.

Features

- High current Triac
- High immunity level
- Low thermal resistance with dip bounding
- RoHS (2002/95/EC) compliant package
- Very high commutation (3Q) at 150 °C capability
- UL certified (ref. file E81734)

Applications

Thanks to its high electrical noise immunity level and its strong current robustness, the T30xxH series is designed for the control of AC actuators in appliances and industrial systems.

Description

Specifically designed to operate at 150 °C, the new 30 A T300cH Triacs provide very high dynamic performance and enhanced performance in terms of power loss and thermal dissipation. This allows optimizing the heatslink size, leading to space and cost effectiveness when compared to electro-mechanical solutions.

Based on ST Snubberless™ technology, they offer a specified minimal commutation and high noise immunity levels valid up to the T₁ max.

The T90xxH series optimize safely the control of universal motors and of inductive loads found in power tools and major appliances.

By using an internal ceramic pad, the T30xxH-6I provides voltage insulation (rated at 2500 V rms).

TM: Snubberless is a trademark of STM croelectronics



Doc ID 17029 Rev 4

1/0





T2035H, T2050H

High temperature 20 A Snubberless™ Triacs

Features

- Medium current Triac
- 150 °C max. T_i turn-off commutation
- Low thermal resistance with clip bonding
- Very high 3 quadrant commutation capability
- Packages are RoHS (2002/95/EC) compliant
- UL certified (ref. file E81734)

Applications

Especially designed to operate in high power density or universal motor applications such as vacuum cleaner and washing machine drum motor.

Description

Available in through-hole and surface mount packages, the T2035H and T2050H Triac series are suitable for general purpose mains power AC switching.

These 20 A Triacs provide a very high switching capability up to junction temperatures of 150 °C.

The heatsink can be reduced, compared to traditional Triacs, according to the high performance at given junction temperatures.

By using an internal ceramic pad, the T20xxH-6I provides voltage insulation (rated at 2500 V rms).



Table 1. Device summary

Symbol	Value	Unit
I _{T(FMS)}	20	A
V _{DRM} /V _{RRM}	600	v
IGT	35 or 50	mA

TM: Snubberless is a trademark of STMicroelectronics

August 2011

Doc ID 13575 Rev 3

1/10





DESCRIPTION

Designed to protect against battery reversal and load dump overvoltages in automotive applica-tions, this monolithic component offers multiple functions in the same package : D1 : reversed battery protection T1 : clamping against negative overvoltages T2 : Transil function against "load dump" effect.

TO220-AB RBO40-40T

FUNCTIONAL DIAGRAM



TM : TRANSIL and ASD are trademarks of STMicroelectronics.

September 2005 - Ed:6

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STTH812

Ultrafast recovery - 1200 V diode

Main product characteristics

I _{F(AV)}	8 A
VREM	1200 V
т	175° C
V _F (typ)	1.25 V
t _{rr} (typ)	50 ns

Features and benefits

- Ultratast, soft recovery
- Very low conduction and switching losses
- High frequency and/or high pulsed current operation
- High reverse voltage capability
- High junction temperature
- Insulated packages:
 - TO-220Ins Electrical Insulation = 2500 V_{RMS} Capacitance = 7 pF
 - TO-220FPAC Electrical insulation = 2000 V_{FMS} Capacitance = 12 pF

Description

The high quality design of this diode has produced a device with low leakage current, regularly reproducible characteristics and intrinsic ruggedness. These characteristics make it ideal for heavy duty applications that demand long term reliability.

Such demanding applications include industrial power supplies, motor control, and similar mission-critical systems that require rectification and freewheeling. These diodes also fit into auxiliary functions such as snubber, bootstrap, and demagnetization applications.

The improved performance in low leakage current, and therefore thermal runaway guard band, is an immediate competitive advantage for this device.



Rev 1

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Order codes

Part Number	Marking
STTHe12D	STTH812D
STTH812G	STTH812G
STTHs12G-TR	STTHe12G
STTHs12FP	STTH812FP
STTHe12DI	STTH812DI





TO-220AC Ins STTH12T06D1

Table 1. Device summary

Value

12 A

600 V

15 ns

2.3 A

2.05 V

65 A

175 °C

Symbol

F(AV)

VRRM

t_{er} (typ)

I_{RM} (typ)

VF (typ)

FRM

T_j (max)

STTH12T06

600 V tandem extra fast diode

Datacheet - production data

Features

- High voltage rectifier
- Tandem diodes in series
- · Very low switching losses
- Insulated device with Internal ceramic
- · Equal thermal conditions for both 300 V diodes
- Static and dynamic equilibrium of internal diodes are warranted by design
- Insulated package:
 - Capacitance: 7 pF
 - Insulated voltage: 2500 V ms

Description

This device is part of ST's second generation of 600 V tandem diodes. It has ultraiow switchinglosses with a minimized Ω_{RR} (6.5 nC) that makes it perfect for use in circuits working in hardswitching mode. In particular the V_P/ Ω_{RR} trade-off positions this device between standard ultrafast diodes and silicon-carbide Schottky rectifiers in terms of price/performance ratio.

The device offers a new positioning giving more flexibility to power-circuit designers looking for good performance while still respecting cost constraints.

Featuring ST's Turbo 2 600 V technology, the device is particularly suited as a boost diode in continuous conduction mode power factor correction circuits.

May 2013

Doc ID024431 Rev1

This is information on a product in full production.

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www.at.com



4 TESTS RESULTS SUMMARY

4.1 <u>Test vehicles</u>

TRIAC: 7 test vehicles were chosen:

- BTA24-800BWRG
- BTB24-600BWRG
- BTB24-800BWRG
- T2050H-6T
- T2535-600G
- T2035H-6G

RECTIFIER: 2 test vehicles were chosen:

- STTH812DI
- STTH12T06DI

Lot #	Part Number	Process/ Package	Comments
LOT 1	BTA24-800BWRG	TO-220AB Insulated	Qualification lot
LOT 2	BTA24-800BWRG	TO-220AB Insulated	Qualification Lot
LOT 3	BTB24-600BWRG	TO-220AB None Insulated	Qualification Lot
LOT 4	BTB24-800BWRG	TO-220AB None Insulated	Qualification Lot
LOT 5	T3035-450I	TO-220AB Insulated	Qualification Lot
LOT 6	T2050H-6T	TO-220AB None Insulated	Qualification Lot
LOT 7	T2050H-6T	TO-220AB None Insulated	Qualification Lot
LOT 8	T2035H-6G	D²PAK	Qualification Lot
LOT 9	T2035H-6G	D²PAK	Qualification Lot
LOT 10	T2535-600G	D²PAK	Qualification Lot
LOT 11	STTH12T06DI	TO-220AC Insulated	Qualification Lot
LOT 12	STTH812DI	TO-220AC Insulated	Qualification Lot



4.2 Test plan and result summary

BTA24-800BWRG

TEST	STD ref.	Conditions	SS	Steps	LOT 1	LOT 2		
	JESD22 A-108	T _i = 125 °C		168 h	0/77	-		
HTRB	MIL-STD-750C	V = VDRM rated (AC	77	500 h	0/77	-		
	method 1040	peak)		1000 h	0/77	-		
		85 °C		168 h	0/25	0/25		
тнв	JESD22 A-101 V _r = 200 V 1000 h	V _r = 200 V			50	500 h	0/25	0/25
				1000 h	0/25	0/25		
тс	JESD22 A-104	-65 °C/+150 °C 2 cycles/h 500 cycles	50	500 cycles	0/25	0/25		
Solderability	J STD-002	Steam aging bath SnAgCu 245°C	20	8 hours	0/20	-		
Solderability	J STD-002	Steam aging bath SnPb-220°C	20	8 hours	0/20	-		
RSH	JESD22 B-106-A	260°C 10S 2 immersions	12	2 dipping	0/12	-		
Screwing	ST 0063378	Torque 0.5 N.m/20µm	10	1 Torque	0/10	-		

BTA24-600BWRG

TEST	STD ref.	Conditions	SS	Steps	LOT 3
	JESD22 A-108	T _i = 125 °C		168 h	0/77
HTRB	MIL-STD-750C	V = VDRM rated (AC	77	500 h	0/77
	method 1040	peak)		1000 h	0/77
		85 °C		168 h	0/25
тнв	JESD22 A-101	85% RH V _r = 200 V	25	500 h	0/25
		1000 h		1000 h	0/25
тс	JESD22 A-104	-65 °C/+150 °C 2 cycles/h 500 cycles	25	500 cycles	0/25
Screwing	ST 0063378	Torque 0.5 N.m/20µm	10	1 Torque	0/10



BTB24-800BWRG

TEST	STD ref.	Conditions	SS	Steps	LOT 4
	JESD22 A-108	T _i = 125 °C		168 h	0/77
HTRB	MIL-STD-750C	V = VDRM rated (AC	77	500 h	0/77
	method 1040	peak)		1000 h	0/77
		85 °C		168 h	0/25
тнв	JESD22 A-101	01 85% RH V _r = 200 V 1000 h	25	500 h	0/25
				1000 h	0/25
тс	JESD22 A-104	-65 °C/+150 °C 2 cycles/h 500 cycles	25	500 cycles	0/25
Solderability	J STD-002	Steam aging bath SnAgCu 245°C	20	8 hours	0/20
Solderability	J STD-002	Steam aging bath SnPb-220°C	20	8 hours	0/20
RSH	JESD22 B-106-A	260°C 10S 2 immersions	12	2 dipping	0/12

<u>T3035-450I</u>

TEST	STD ref.	Conditions	SS	Steps	LOT 5
	JESD22 A-108	T _j = 150 °C V = VDRM rated (AC peak)		168 h	0/77
HTRB	MIL-STD-750C		77	500 h	0/77
	method 1040			1000 h	0/77



<u>T2050H-6T</u>

TEST	STD ref.	Conditions	SS	Steps	LOT 6	LOT 7	
	JESD22 A-108	T _i = 150 °C		168 h	0/77	0/40	
HTRB	MIL-STD-750C	V = VDRM rated (AC	117	500 h	0/77	0/40	
	method 1040	peak))40 peak)		1000 h	0/77	0/40
	85 °C	85 °C		168 h	0/25	0/25	
тнв	JESD22 A-101	85% RH Vr = 200 V	JESD22 A-101 85% RH V _r = 200 V	50	500 h	0/25	0/25
		1000 h		1000 h	0/25	0/25	
тс	JESD22 A-104	-65 °C/+150 °C 2 cycles/h 500 cycles	50	500 cycles	0/25	0/25	

<u>T2035H-6G</u>

TEST	STD ref.	Conditions	SS	Steps	LOT 8	LOT 9
				erebe		
MSL Evaluation	J-STD-020D.01	MSL1 85 °C,85% RH 168 h MSL3 30 °C60% RH 192 h	50	168 h 192 h	0/25 0/25	0/25 0/25
		85 °C		168 h	0/25	0/25
PC + THB	JESD22 A-101	85% RH V _r = 200 V 5	50	50 500 h	0/25	0/25
		1000 h		1000 h	0/25	0/25
PC + TC	JESD22 A-104	-65 °C/+150 °C 2 cycles/h 500 cycles	50	500 cycles	0/25	0/25
Solderability	J STD-002	Dry aging bath SnAgCu 245°C	10	16 hours	0/10	-
Solderability	J STD-002	Steam aging bath SnAgCu-245°C	10	8 hours	0/10	-
Solderability	J STD-002	Dry aging bath SnPb 220°C	10	16 hours	0/10	-
Solderability	J STD-002	Steam aging bath SnPb-220°C	10	8 hours	0/10	-
RSH	JESD22 B-106-A	260°C 10S 2 immersions	12	2 dipping	-	0/12



T2535-600G/7

TEST	STD ref.	Conditions	SS	Steps	LOT 10
MSL Evaluation	J-STD-020D.01	MSL1 85 ℃,85% RH 168 h MSL3 30 ℃60% RH 192 h		168 h 192 h	0/25 0/25
		85 °C		168 h	0/25
PC + THB	JESD22 A-101	85% RH V _r = 200 V	25	500 h	0/25
		1000 h		1000 h	0/25
PC + TC	JESD22 A-104	-65 °C/+150 °C 2 cycles/h 500 cycles	50	500 cycles	0/25

<u>STTH812DI</u>

TEST	STD ref.	Conditions	SS	Steps	LOT 11
HTRB	JESD22 A-108	T _j = 150 °C VR = 960V	77	168 h	0/77
IIIKB	MIL-STD-750C method 1040	500 h	//	500 h	0/77
		85 °C		168 h	0/25
тнв	JESD22 A-101	85% RH V _r = 100 V 2	25	500 h	0/25
		1000 h		1000 h	0/25
тс	JESD22 A-104	-65 °C/+150 °C 2 cycles/h 500 cycles	25	500 cycles	0/25
AC	JESD22 A-102	121°C, 2,05 bars	25	96 h	0/25
RSH	JESD22 B-106-A	260°C 10S 2 immersions	12	2 dipping	0/12



STTH12T06DI

TEST	STD ref.	Conditions	SS	Steps	LOT 12
	JESD22 A-108	T _i = 150 °C		168 h	0/77
HTRB	MIL-STD-750C method 1040	V = 80% VBR	77	500 h	0/77
		85 °C		168 h	0/25
тнв	JESD22 A-101	85% RH V _r = 100 V	25	500 h	0/25
		1000 h		1000 h	0/25
тс	JESD22 A-104	-65 °C/+150 °C 2 cycles/h 500 cycles	25	500 cycles	0/25
AC	JESD22 A-102	121°C, 2,05 bars	25	96 h	0/25
RSH	JESD22 B-106-A	260°C 10S 2 immersions	12	2 dipping	0/12



5 APPENDIX

5.1 Device details

5.1.1 Pin connection



5.1.2 Package outline/Mechanical data

TRIAC

	TO 33945				DIMEN	SIONS		
TO-220AB		REF.	м	illimete	rs	Inches		
			Min.	тур.	Max.	Min.	Тур.	Max.
		Α	15.20		15.90	0.598		0.625
		a1		3.75			0.147	
B	C .	a2	13.00		14.00	0.511		0.551
	<u>b2</u>	В	10.00		10.40	0.393		0.409
	-# F	b1	0.61		0.88	0.024		0.034
A		b2	1.23		1.32	0.048		0.051
l4 l3		С	4.40		4.60	0.173		0.181
	c2	c1	0.49		0.70	0.019		0.027
12 a2		c2	2.40		2.72	0.094		0.107
		е	2.40		2.70	0.094		0.106
	M	F	6.20		6.60	0.244		0.259
"e"		ØI	3.75		3.85	0.147		0.151
		14	15.80	16.40	16.80	0.622	0.646	0.661
		L	2.65		2.95	0.104		0.116
		12	1.14		1.70	0.044		0.066
		13	1.14		1.70	0.044		0.066
		М		2.60			0.102	

TRIAC & PROTECTION families

					DIMEN	SIONS		
I	D ² PAK			illimete	rs		Inches	
			Min.	Тур.	Max.	Min.	Тур.	Max.
	<u>⊢ A →</u>	Α	4.30		4.60	0.169		0.181
	C2→++-	A1	2.49		2.69	0.098		0.106
		A2	0.03		0.23	0.001		0.009
	D	В	0.70		0.93	0.027		0.037
⊾		B2	1.25	1.40		0.048	0.055	
	A1	С	0.45		0.60	0.017		0.024
±		C2	1.21		1.36	0.047		0.054
	$\langle \rangle$	D	8.95		9.35	0.352		0.368
G		Е	10.00		10.28	0.393		0.405
	2mm min. FLAT ZONE	G	4.88		5.28	0.192		0.208
		L	15.00		15.85	0.590		0.624
	V2	L2	1.27		1.40	0.050		0.055
		L3	1.40		1.75	0.055		0.069
		R		0.40			0.016	
		V2	0 °		8°	0°		8°



RECTIFIER family

					Dimer	sions		
TO-220AC	F	Ref.	. Millimeters			Inches		
			Min.	Тур.	Max.	Min.	Тур.	Max.
	Г	Α	15.20		15.90	0.598		0.625
в	c	a1		3.75			0.147	
01 b2.		a2	13.00		14.00	0.511		0.551
		В	10.00		10.40	0.393		0.409
		b1	0.61		0.88	0.024		0.034
н А.	1 [b2	1.23		1.32	0.048		0.051
		С	4.40		4.60	0.173		0.181
	°≟.	c1	0.49		0.70	0.019		0.027
12 a2		c2	2.40		2.72	0.094		0.107
		0	4.80		5.40	0.189		0.212
	e1	F	6.20		6.60	0.244		0.259
1- 0-1	Γ	ØI	3.75		3.85	0.147		0.151
		14	15.80	16.40	16.80	0.622	0.646	0.661
	Γ	L	2.65		2.95	0.104		0.116
		12	1.14		1.70	0.044		0.066
		М		2.60			0.102	



5.2 <u>Test Descriptions</u>

Test name	Description	Purpose
	Die-oriented test	
HTRB (AC mode)	The device is stressed here in AC mode, trying to satisfy as much as possible the following conditions:	To determine the effects of bias conditions and temperature on solid state devices over time. It simulates the devices operating condition in an accelerated way.
High Temperature Reverse Bias	 Low power dissipation. Peak supply voltage compatible with diffusion process and internal circuitry limitations. 	To maximize the electrical field across either reverse- biased junctions or dielectric layers, in order to investigate the failure modes linked to mobile contamination, oxide aging, layout sensitivity to surface effects.
HTRB High Temperature Reverse Bias	The device is stressed in static configuration, trying to satisfy as much as possible the following conditions: low power dissipation; max. supply voltage compatible with diffusion process and internal circuitry limitations;	To determine the effects of bias conditions and temperature on solid state devices over time. It simulates the devices operating condition in an accelerated way. To maximize the electrical field across either reverse- biased junctions or dielectric layers, in order to investigate the failure modes linked to mobile contamination, oxide ageing, layout sensitivity to surface effects.
	Die and Package-oriente	d test
THB Temperature Humidity Bias	The device is biased in static configuration minimizing its internal power dissipation, and stored at controlled conditions of ambient temperature, and relative humidity.	To evaluate the package moisture resistance with electrical field applied, both electrolytic and galvanic corrosion are put in evidence.
TC Temperature Cycling	The device is submitted to cycled temperature excursions, between a hot and a cold chamber in air atmosphere.	To investigate failure modes related to the thermo- mechanical stress induced by the different thermal expansion of the materials interacting in the die- package system. Typical failure modes are linked to metal displacement, dielectric cracking, molding compound delamination, wire-bonds failure, die- attach layer degradation.
PC Preconditioning	The device is submitted to a typical temperature profile used for surface mounting devices, after a controlled moisture absorption.	verify that the surface mounting stress does not impact on the subsequent reliability performance. The typical failure modes are "pop corn" effect and delamination.
SD Solderability	The device is aged in a wet and dry bath of solder. A preconditioning test is included in this test method, which degrades the termination finish to provide a guard band against marginal finish.	To test whether the packaging materials and processes used during the manufacturing operations process produce a component that can be successfully soldered to the next level assembly using tin lead eutectic solder.
AC Autoclave	The device is stored in saturated steam, at fixed and controlled conditions of pressure and temperature.	
RSH Resistance to Solder Heat	The device is submitted to a dipping in a solder bath at 260 °C with a dwell time of 10 s.	This test is used to determine whether solid state devices can withstand the effects of the temperature to which they will be subjected during soldering of their leads. The heat is conducted through the leads into the device package from solder heat at the reverse side of the board. This procedure does not simulate wave soldering or reflow heat exposure on the same side of the board as the package body.



5.3 List of products involved in this qualification

List 1/3

Parts	Case	Function -	Parts	Case	Function -	Parts	Case	Function
AVSxxxx	TO-220	Triac	BTA10-xxxCWRG	TO-220 insulated	Triac	BTB06-xxxTRG	TO-220	Triac
BTA04-xxxSRG	TO-220 insulated	Triac	BTA10-xxxGPRG	TO-220 insulated	Triac	BTB06-xxxTWRG	TO-220	Triac
BTA04-xxxTRG	TO-220 insulated	Triac	BTA12-xxxBRG	TO-220 insulated	Triac	BTB08-xxxBRG	TO-220	Triac
BTA06T-xxxCWRG	TO-220 insulated	Triac	BTA12-xxxBWRG	TO-220 insulated	Triac	BTB08-xxxBWRG	TO-220	Triac
BTA06-xxxARG	TO-220 insulated	Triac	BTA12-xxxCRG	TO-220 insulated	Triac	BTB08-xxxCRG	TO-220	Triac
BTA06-xxxARG	TO-220 insulated	Triac	BTA12-xxxCWRG	TO-220 insulated	Triac	BTB08-xxxCWRG	TO-220	Triac
BTA06-xxxBRG	TO-220 insulated	Triac	BTA12-xxxGBRG	TO-220 insulated	Triac	BTB08-xxxSRG	TO-220	Triac
BTA06-xxxBRG	TO-220 insulated	Triac	BTA12-xxxSWRG	TO-220 insulated	Triac	BTB08-xxxSWRG	TO-220	Triac
BTA06-xxxBWRG	TO-220 insulated	Triac	BTA12-xxxTWRG	TO-220 insulated	Triac	BTB08-xxxTWRG	TO-220	Triac
BTA06-xxxCRG	TO-220 insulated	Triac	BTA16-xxxBRG	TO-220 insulated	Triac	BTB10-xxxBWRG	TO-220	Triac
BTA06-xxxCWRG	TO-220 insulated	Triac	BTA16-xxxBWRG	TO-220 insulated	Triac	BTB12-xxxBRG	TO-220	Triac
BTA06-xxxGKRG	TO-220 insulated	Triac	BTA16-xxxCRG	TO-220 insulated	Triac	BTB12-xxxBWRG	TO-220	Triac
BTA06-xxxGPRG	TO-220 insulated	Triac	BTA16-xxxCWRG	TO-220 insulated	Triac	BTB12-xxxCRG	TO-220	Triac
BTA06-xxxGVRG	TO-220 insulated	Triac	BTA16-xxxSWRG	TO-220 insulated	Triac	BTB12-xxxCWRG	TO-220	Triac
BTA06-xxxGZRG	TO-220 insulated	Triac	BTA20-xxxBWRG	TO-220 insulated	Triac	BTB12-xxxSWRG	TO-220	Triac
BTA06-xxxSRG	TO-220 insulated	Triac	BTA20-xxxCWRG	TO-220 insulated	Triac	BTB12-xxxTWRG	TO-220	Triac
BTA06-xxxSWRG	TO-220 insulated	Triac	BTA20-xxxWH	TO-220 insulated	Triac	BTB15-xxxBAKRG	TO-220	Triac
BTA06-xxxTRG	TO-220 insulated	Triac	BTA24-xxxBWL	TO-220 insulated	Triac	BTB16-xxxBRG	TO-220	Triac
BTA06-xxxTWRG	TO-220 insulated	Triac	BTA24-xxxBWLRG	TO-220 insulated	Triac	BTB16-xxxBWARG	TO-220	Triac
BTA08-xxx300xx	TO-220 insulated	Triac	BTA24-xxxBWRG	TO-220 insulated	Triac	BTB16-xxxBWRG	TO-220	Triac
BTA08-xxxBRG	TO-220 insulated	Triac	BTA24-xxxCWRG	TO-220 insulated	Triac	BTB16-xxxCRG	TO-220	Triac
BTA08-xxxBWRG	TO-220 insulated	Triac	BTA24-xxxGPLRG	TO-220 insulated	Triac	BTB16-xxxCWRG	TO-220	Triac
BTA08-xxxCRG	TO-220 insulated	Triac	BTB04-xxxSAPRG	TO-220	Triac	BTB16-xxxSWRG	TO-220	Triac
BTA08-xxxCWRG	TO-220 insulated	Triac	BTB04-xxxTRG	TO-220	Triac	BTB24-xxxBAKRG	TO-220	Triac
BTA08-xxxSRG	TO-220 insulated	Triac	BTB06-xxxBRG	TO-220	Triac	BTB24-xxxBRG	TO-220	Triac
BTA08-xxxSWRG	TO-220 insulated	Triac	BTB06-xxxBWRG	TO-220	Triac	BTB24-xxxBWRG	TO-220	Triac
BTA08-xxxTWRG	TO-220 insulated	Triac	BTB06-xxxCRG	TO-220	Triac	BTB24-xxxCWRG	TO-220	Triac
BTA10-xxxBRG	TO-220 insulated	Triac	BTB06-xxxCWRG	TO-220	Triac	T1010H-6G	D ² PAK	Triac
BTA10-xxxBWRG	TO-220 insulated	Triac	BTB06-xxxDRG	TO-220	Triac	T1010H-6T	TO-220	Triac
BTA10-xxxCRG	TO-220 insulated	Triac	BTB06-xxxSWRG	TO-220	Triac	T1035H-6G	D ² PAK	Triac



List 2/3

Parts	Case	Function -	Parts	Case	Function -	Parts	Case	Function
T1035H-6G-TR	D ² PAK	Triac	T1635-600G	D ² PAK	Triac	T410H-6T	TO-220	Triac
T1035H-6I	TO-220 insulated	Triac	T1635-600G-TR	D ² PAK	Triac	T410-xxxT	TO-220	Triac
T1035H-6T	TO-220	Triac	T1635-700G-TR	D ² PAK	Triac	T435-xxxT	TO-220	Triac
T1050H-6G	D ² PAK	Triac	T1635-800G-TR	D ² PAK	Triac	T610H-6T	TO-220	Triac
T1050H-6T	TO-220	Triac	T1635H-6G	D ² PAK	Triac	T810-600G-TR	D ² PAK	Triac
T1205-600G-TR	D²PAK	Triac	T1635H-6G-TR	D ² PAK	Triac	T810H-6G	D ² PAK	Triac
T1210-800G-TR	D ² PAK	Triac	T1635H-6I	TO-220 insulated	Triac	T810H-6G-TR	D ² PAK	Triac
T1210T-6I	TO-220 insulated	Triac	T1635H-6T	TO-220	Triac	T810H-6T	TO-220	Triac
T1220T-6I	TO-220 insulated	Triac	T1635T-6I	TO-220 insulated	Triac	T810T-6I	TO-220 insulated	Triac
T1225T-6I	TO-220 insulated	Triac	T1635T-8I	TO-220 insulated	Triac	T820T-6I	TO-220 insulated	Triac
T1235-600G	D²PAK	Triac	T1650-600G-TR	D ² PAK	Triac	T825T-6I	TO-220 insulated	Triac
T1235-600G-TR	D²PAK	Triac	T1650H-6G	D ² PAK	Triac	T835-600G	D ² PAK	Triac
T1235-800G-TR	D²PAK	Triac	T1650H-6I	TO-220 insulated	Triac	T835-600G-TR	D²PAK	Triac
T1235H-600TRG	TO-220	Triac	T1650H-6T	TO-220	Triac	T835H-6G	D ² PAK	Triac
T1235H-6G	D²PAK	Triac	T1650HT-6I	TO-220 insulated	Triac	T835H-6G-TR	D ² PAK	Triac
T1235H-6G-TR	D²PAK	Triac	T2035H-6G	D ² PAK	Triac	T835H-6I	TO-220 insulated	Triac
T1235H-6I	TO-220 insulated	Triac	T2035H-6G-TR	D ² PAK	Triac	T835H-6T	TO-220	Triac
T1235H-6T	TO-220	Triac	T2035H-6I	TO-220 insulated	Triac	T835T-6I	TO-220 insulated	Triac
T1235T-6I	TO-220 insulated	Triac	T2035H-6T	TO-220	Triac	T850H-6G	D ² PAK	Triac
T1250-600G-TR	D²PAK	Triac	T2050H-6T	TO-220	Triac	T850H-6G-TR	D ² PAK	Triac
T1250H-6G-TR	D²PAK	Triac	T2535-600G	D ² PAK	Triac	T850H-6I	TO-220 insulated	Triac
T1250H-6I	TO-220 insulated	Triac	T2535-600G-TR	D ² PAK	Triac	T850H-6T	TO-220	Triac
T1250H-6T	TO-220	Triac	T2535-800G	D ² PAK	Triac	TB08A6C	TO-220	Triac
T1610-600G-TR	D²PAK	Triac	T2535-800G-TR	D²PAK	Triac	TB08C6CM	TO-220 insulated	Triac
T1610-800G-TR	D²PAK	Triac	T2550H-600TRG	TO-220	Triac	TB12A6C	TO-220	Triac
T1610T-6I	TO-220 insulated	Triac	T3035H-6I	TO-220 insulated	Triac	TB12C6CM	TO-220 insulated	Triac
T1610T-8I	TO-220 insulated	Triac	T3035H-6T	TO-220	Triac	TB16A6D	D ² PAK	Triac
T1620T-6I	TO-220 insulated	Triac	T3050H-6I	TO-220 insulated	Triac	TB16A6Y	TO-220	Triac
T1620T-8I	TO-220 insulated	Triac	T3050H-6T	TO-220	Triac	TB16C6C	TO-220 insulated	Triac
T1625T-8I	TO-220 insulated	Triac	T405-xxxT	TO-220	Triac	TB16C6CM	TO-220 insulated	Triac



List 3/3

Parts	Case	Function
TB25A6C	TO-220	Triac
TB25A6D	D ² PAK	Triac
TB25C6CM	TO-220 insulated	Triac
TXDVxxxRG	TO-220 insulated	Triac
TN1205H-6G	D ² PAK	Scr
TN1205H-6G-TR	D ² PAK	Scr
TN1205H-6T	TO-220	Scr
TN1215-xxxG	D ² PAK	Scr
TN1215-xxxG-TR	D ² PAK	Scr
TN1625-xxxG-TR	D ² PAK	Scr
TN2540-xxxG-TR	D ² PAK	Scr
TXNxx12RG	TO-220 insulated	Scr
TXNxx25RG	TO-220 insulated	Scr
TYNx12DTRG	TO-220	Scr
TYNx16SRG	TO-220	Scr
TYNxx10RG	TO-220	Scr
TYNxx12RG	TO-220	Scr
TYNxx12TRG	TO-220	Scr
TYNxx16RG	TO-220	Scr
TYNxx25RG	TO-220	Scr
TYNxx40RG	TO-220	Scr
TYNxx4RG	TO-220	Scr
TYNxx6RG	TO-220	Scr
TYNxx8BDRG	TO-220	Scr
TYNxx8RG	TO-220	Scr

BYT08PI-400RG	D²PAK	Rectifier
STPSC10TH13TI	TO-220 insulated	Rectifier
STPSC6TH13TI	TO-220 insulated	Rectifier
STPSC8TH13TI	TO-220 insulated	Rectifier
STTHxxxDTI	TO-220 insulated	Rectifier
STTHxxxTTI	TO-220 insulated	Rectifier
STTHxxxDI	TO-220 insulated	Rectifier
STTH12R06DIRG	TO-220 insulated	Rectifier
STTHxxT06DI	TO-220 insulated	Rectifier
STTH806DIRG	TO-220 insulated	Rectifier
STTH8R04DI	TO-220 insulated	Rectifier
STTH8R06DIRG	TO-220 insulated	Rectifier
STTH8ST06DI	TO-220 insulated	Rectifier
STTH8T06TI	TO-220 insulated	Rectifier

RBO08-40G	D ² PAK	ASD
RBO08-40G-TR	D ² PAK	ASD
RBO40-40G	D ² PAK	ASD
RBO40-40G-TR	D ² PAK	ASD



PCN Title : New ECOPACK2 molding compound for selected products housed in TO-220AB, TO-220AB insulated, TO-220AC insulated and D2P PCN Reference : IPD-DIS/13/7944 PCN Created on : 21-JUN-2013

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change:

ST COMMERCIAL PRODUCT

AVS12CB BTA06-600CRG BTA06-600TWRG BTA06-800TWRG BTA08-600BWRG BTA08-600SWRG BTA08-800CRG BTA10-600CRG BTA10-800BWRG BTA12-600BWRG BTA12-600SWRG BTA12-800BWRG BTA16-600BRG BTA16-600CWRG BTA16-800BRG BTA20-600CWRG BTA24-600BWRG BTA24-800CWRG BTB06-600CRG BTB06-600TWRG BTB08-600CRG BTB08-600TWRG BTB10-600BWRG BTB12-600BWRG BTB12-600SWRG BTB16-600BRG BTB16-600CWRG BTB16-800BWRG BTB24-600BRG BTB24-800BRG RB008-40G STTH1008DTI STTH12R06DIRG STTH2002DI STTH806DTI



PCN Title : New ECOPACK2 molding compound for selected products housed in TO-220AB, TO-220AB insulated, TO-220AC insulated and D2P PCN Reference : IPD-DIS/13/7944 PCN Created on : 21-JUN-2013

Subject : Public Products List (Contd.)

ST COMMERCIAL PRODUCT

STTH806TTI STTH8R04DI STTH8T06DI T1010H-6T T1035H-6I T1050H-6G-TR T1210-800G-TR T1225T-6I T1235-800G-TR T1235H-6G-TR T1235T-6I T1250H-6I T1610-800G-TR T1620T-6I T1635-600G T1635H-6G-TR T1635T-6I T1650H-6G-TR T2035H-6G T2035H-6T T2535-600G-TR T3035H-6T T405-600T T410-800T T435-800T T810H-6G T810T-6I T835-600G T835H-6G-TR T835T-6I T850H-6I TN1205H-6G-TR TN1215-600G-TR TN1625-600G-TR TXDV1212RG

STTH810DI STTH8R06DIRG T1010H-6G T1035H-6G T1035H-6T T1050H-6I T1210T-6I T1235-600G T1235H-600TRG T1235H-6I T1250H-6G T1250H-6T T1610T-6I T1620T-8I T1635-600G-TR T1635H-6I T1635T-8I T1650H-6I T2035H-6G-TR T2050H-6T T2535-800G T3050H-6I T410-600T T410H-6T T610H-6T T810H-6G-TR T820T-6I T835-600G-TR T835H-6I T850H-6G T850H-6T TN1205H-6T TN1215-800G-TR TN2540-600G-TR

TXDV812RG

STTH812DI STTH8ST06DI T1010H-6G-TR T1035H-6G-TR T1050H-6G T1050H-6T T1220T-6I T1235-600G-TR T1235H-6G T1235H-6T T1250H-6G-TR T1610-600G-TR T1610T-8I T1625T-8I T1635H-6G T1635H-6T T1650H-6G T1650H-6T T2035H-6I T2535-600G T3035H-6I T3050H-6T T410-700T T435-600T T810-600G-TR T810H-6T T825T-6I T835H-6G T835H-6T T850H-6G-TR TN1205H-6G TN1215-600G TN1625-1000G-TR TN2540-800G-TR



PCN Title : New ECOPACK2 molding compound for selected products housed in TO-220AB, TO-220AB insulated, TO-220AC insulated and D2P PCN Reference : IPD-DIS/13/7944 PCN Created on : 21-JUN-2013

Subject : Public Products List (Contd.)

ST COMMERCIAL PRODUCT

TXN625RG	TYN1012RG	TYN1012TRG
TYN1212RG	TYN1225RG	TYN606RG
TYN608RG	TYN610RG	TYN612RG
TYN612TRG	TYN616RG	TYN625RG
TYN640RG	TYN812RG	TYN812TRG
TYN816RG	TYN825RG	TYN840RG

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